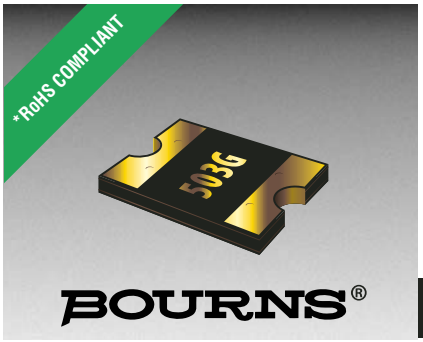


Features

- Very low profile
- Very fast tripping time
- High voltage
- RoHS compliant*
- Symmetrical
- 2018 footprint
- Agency recognition:

Applications

- Power Over Ethernet (IEEE 802.3 af) port protection
- Automotive electronic control module protection
- Telecom equipment low voltage protection

MF-SMDF Series - PTC Resettable Fuses

Electrical Characteristics

Model	V max. Volts	I max. Amps	I_{hold}	I_{trip}	Resistance		Max. Time To Trip		Tripped Power Dissipation
			Amperes at 23 °C		Ohms at 23 °C		Amperes at 23 °C	Seconds at 23 °C	Watts at 23 °C
			Hold	Trip	$R_{Min.}$	$R_{1Max.}$			Typ.
MF-SMDF050	60	10	0.55	1.20	0.200	1.0	2.5	3.0	0.9
MF-SMDF100*	15	40	1.1	2.20	0.06	0.36	8.0	0.4	1.0
MF-SMDF150*	15	40	1.5	3.00	0.05	0.17	8.0	0.8	1.1
MF-SMDF200	10	40	2.0	4.00	0.03	0.100	8.0	2.40	1.1

*Agency approval pending.

Environmental Characteristics

Operating Temperature .....-40 °C to +85 °C
Maximum Device Surface Temperature in Tripped State .....125 °C
Passive Aging.....+85 °C, 1000 hours .....±5 % typical resistance change
Humidity Aging.....+85 °C, 85 % R.H. 1000 hours .....±5 % typical resistance change
Thermal Shock.....+85 °C to -40 °C, 20 times .....±10 % typical resistance change
Solvent Resistance .....MIL-STD-202, Method 215 .....No change
Vibration.....MIL-STD-883C, Method 2007.1, Condition A .....No change

Test Procedures And Requirements For Model MF-SMDF Series

Test	Test Conditions	Accept/Reject Criteria
Visual/Mech	Verify dimensions and materials	Per MF physical description
Resistance	In still air @ 23 °C	Rmin ≤ R ≤ R1max
Time to Trip	At specified current, Vmax, 23 °C	T ≤ max. time to trip (seconds)
Hold Current	30 min. at Ihold	No trip
Trip Cycle Life	Vmax, Imax, 100 cycles	No arcing or burning
Trip Endurance	Vmax, 48 hours	No arcing or burning
Solderability	ANSI/J-STD-002	95 % min. coverage

UL File Number.....E174545
http://www.ul.com/ Follow link to Certifications, then UL File No., enter E174545
CSA File Number CA110338
http://directories.csa-international.org/ Under “Certification Record” and “File Number” enter 110338-0-000
TÜV Certificate Number .....R 02057213
http://www.tuvdotcom.com/ Follow link to “other certificates”, enter File No. 2057213

Thermal Derating Chart - I_{hold} / I_{trip} (Amps)

Model	Ambient Operating Temperature								
	-40 °C	-20 °C	0 °C	23 °C	40 °C	50 °C	60 °C	70 °C	85 °C
MF-SMDF050	0.87 / 1.90	0.77 / 1.68	0.67 / 1.46	0.55 / 1.20	0.46 / 1.00	0.41 / 0.89	0.36 / 0.79	0.31 / 0.68	0.23 / 0.50
MF-SMDF100	1.71 / 3.42	1.52 / 3.04	1.32 / 2.64	1.10 / 2.20	0.94 / 1.88	0.84 / 1.68	0.74 / 1.48	0.64 / 1.28	0.50 / 1.00
MF-SMDF150	2.38 / 4.76	2.10 / 4.20	1.82 / 3.64	1.50 / 3.00	1.27 / 2.54	1.13 / 2.26	0.99 / 1.98	0.85 / 1.70	0.64 / 1.28
MF-SMDF200	2.95 / 5.90	2.65 / 5.30	2.35 / 4.70	2.00 / 4.00	1.74 / 3.48	1.59 / 3.18	1.44 / 2.88	1.29 / 2.58	1.06 / 2.12

*RoHS Directive 2002/95/EC Jan 27 2003 including Annex
Specifications are subject to change without notice.
Customers should verify actual device performance in their specific applications.

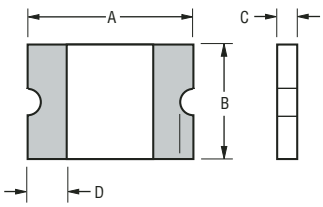
Product Dimensions

Model	A		B		C		D
	Min.	Max.	Min.	Max.	Min.	Max.	Min.
MF-SMDF050	4.72 (0.186)	5.44 (0.214)	4.22 (0.166)	4.93 (0.194)	0.79 (0.031)	1.09 (0.043)	0.30 (0.012)
MF-SMDF100	4.72 (0.186)	5.44 (0.214)	4.22 (0.166)	4.93 (0.194)	0.55 (0.022)	0.85 (0.033)	0.30 (0.012)
MF-SMDF150	4.72 (0.186)	5.44 (0.214)	4.22 (0.166)	4.93 (0.194)	0.55 (0.022)	0.85 (0.033)	0.30 (0.012)
MF-SMDF200	4.72 (0.186)	5.44 (0.214)	4.22 (0.166)	4.93 (0.194)	0.55 (0.022)	0.85 (0.033)	0.30 (0.012)

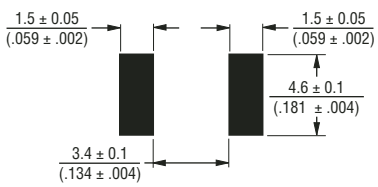
Packaging: 3000 pcs. per reel.

UNIT = MM (INCHES)

Top and Bottom View *Side View*



Recommended Pad Layout

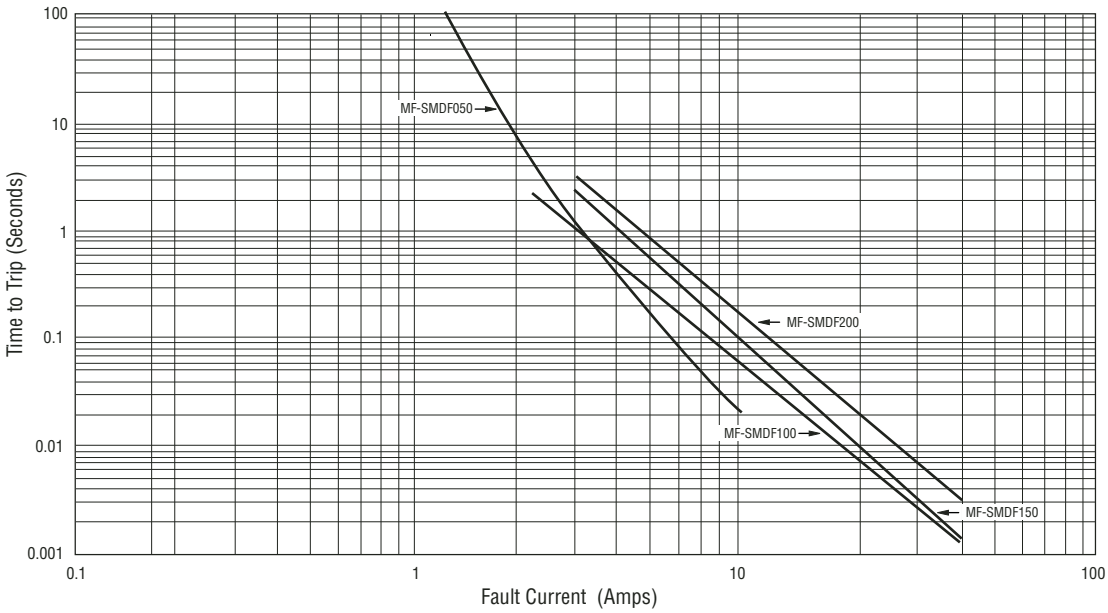


Terminal material:
Electroless Ni under immersion Au

Termination pad solderability:
Standard Au finish:
Meets ANSI/J-STD-002 Category 2.

Recommended Storage:
40 °C max./70 % RH max.

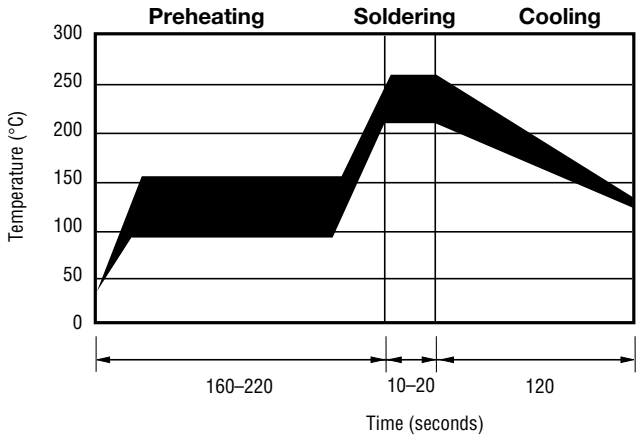
Typical Time to Trip at 23 °C



The Time to Trip curves represent typical performance of a device in a simulated application environment. Actual performance in specific customer applications may differ from these values due to the influence of other variables.

Specifications are subject to change without notice.
Customers should verify actual device performance in their specific applications.

Solder Reflow Recommendations



Notes:

- MF-SMDF models cannot be wave soldered. Please contact Bourns for hand soldering recommendations.
- If reflow temperatures exceed the recommended profile, devices may not meet the performance requirements.
- Compatible with Pb and Pb-free solder reflow profiles.

How to Order

MF - SMDF 050 - 2

Multifuse® Product Designator

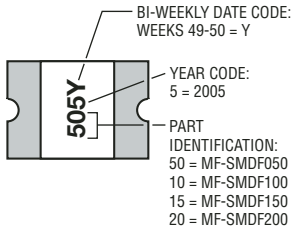
Series
SMDF = 2018 Surface Mount Component

Hold Current, I_{hold}
050, 100, 150, 200 (0.50 - 2.00 Amps)

Packaging
Packaged per EIA 481-1
-2 = Tape and Reel

Typical Part Marking

Represents total content. Layout may vary.

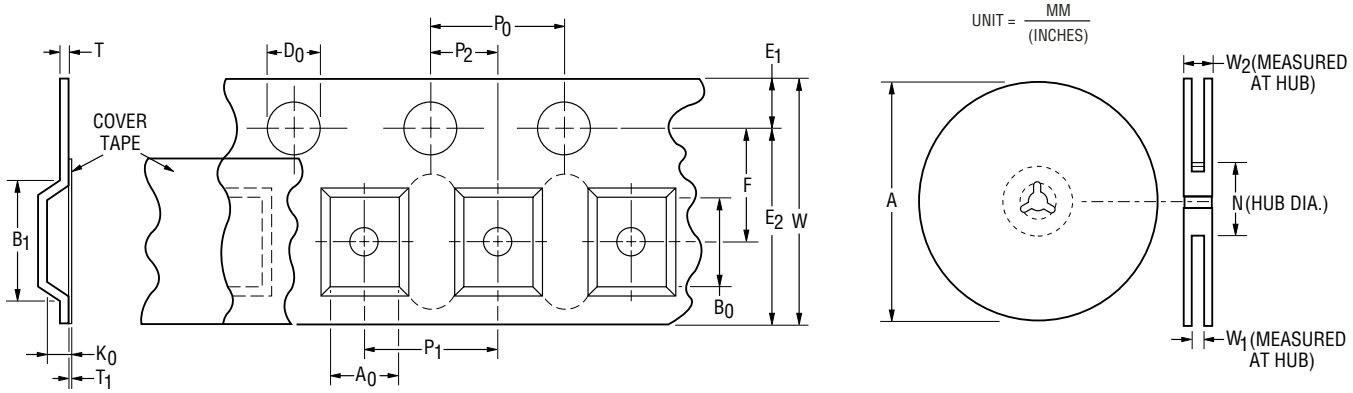


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MF-SMDF Series Tape and Reel Specifications

BOURNS®

Tape Dimensions	MF-SMDF Series per EIA 481-2
W	16.0 ± 0.3 (0.630 ± 0.012)
P_0	4.0 ± 0.1 (0.157 ± 0.004)
P_1	8.0 ± 0.1 (0.315 ± 0.004)
P_2	2.0 ± 0.1 (0.079 ± 0.004)
A_0	5.1 ± 0.15 (0.201 ± 0.006)
B_0	5.6 ± 0.23 (0.220 ± 0.009)
B_1 max.	12.1 (0.476)
D_0	1.5 + 0.1/-0.0 (0.059 + 0.004/-0)
F	7.5 ± 0.10 (0.295 ± 0.004)
E_1	1.75 ± 0.10 (0.069 ± 0.004)
E_2 min.	14.25 (0.561)
T max.	0.6 (0.024)
T_1 max.	0.1 (0.004)
K_0	1.0 ± 0.15 (0.039 ± 0.015)
Leader min.	390 (15.35)
Trailer min.	160 (6.30)
Reel Dimensions	
A max.	331 (13.03)
N min.	50 (1.97)
W_1	16.4 + 2.0/ -0.0 (0.646 + 0.079/-0.0)
W_2 max.	22.4 (0.882)



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